

# Bill of Materials

TI DESIGNS

TIDA-00396

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	C1	0.01uF	CAP, CERM, 0.01 $\mu$ F, 50 V, +/- 10%, X7R, 0603	Kemet	C0603C103K5RACTU		0603	
2	7	J1, J2, J3, J5, J6, J7, J8		Header, 100mil, 2x1, Tin, TH	Sullins Connector Solut	PEC02SAAN		Header, 2 PIN, 100mil, Tin	
3	1	J4		Header, 100mil, 3x1, Tin, TH	Sullins Connector Solut	PEC03SAAN		Header, 3 PIN, 100mil, Tin	
4	1	R1	2.00Meg	RES, 2.00 M, 1%, 0.1 W, 0603	Vishay-Dale	CRCW06032M00FKEA		0603	
5	1	R2	6.81k	RES, 6.81 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW06036K81FKEA		0603	
6	1	R3	30.9k	RES, 30.9 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060330K9FKEA		0603	
7	2	R4, R5	100k	RES, 100 k, 5%, 0.1 W, 0603	Vishay-Dale	CRCW0603100KJNEA		0603	
8	1	R7	100	RES, 100, 1%, 0.1 W, 0603	Vishay-Dale	CRCW0603100RFKEA		0603	
9	1	SH-J1	1x2	Shunt, 100mil, Flash Gold, Black	Sullins Connector Solut	SPC02SYAN		100mil Shunt	
10	5	TP1, TP2, TP3, TP4, TP5	Red	Test Point, Miniature, Red, TH	Keystone	5000		Red Miniature Testpoint	
11	1	U1		36V Window Comparator with Internal Reference for Over and Under Voltage Detection, DDC package	Texas Instruments	TPS3701DDCR		SOT-6	

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